

# 5 Line ESD Protection Diode Array UESD6V85CT36 SC70-6/SC88/SOT363

#### **General Description**

The UESD6V85CT36 of TVS array is designed to protect sensitive electronics from damage or latch-up due to ESD, for use in applications where board space is at a premium. It is unidirectional device and may be used on lines where the signal polarities are above ground, each device will protect up to five lines.

TVS diodes are solid-state devices feature large cross-sectional area junctions for conducting high transient currents, specifically for transient suppression. It offers desirable characteristics for board level protection including fast response time, low clamping voltage, and no device degradation.

The UESD6V85CT36 may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4. The small package makes them ideal for use in portable electronics such as cell phones, PDAs, notebook computers, and digital cameras.

#### **Applications**

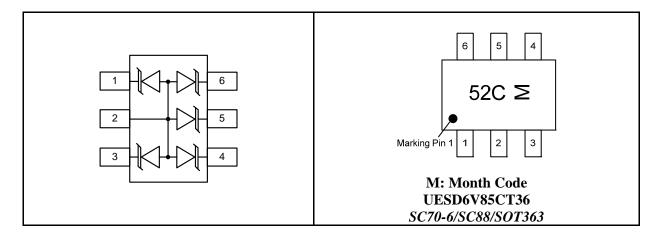
- Cellular Handsets & Accessories
- Cordless Phones
- Personal Digital Assistants(PDAs)
- Notebooks & Handhelds
- Portable Instrumentation
- Digital Cameras
- Peripherals
- MP3 Players

#### **Features**

- Transient Protection for Data Lines to IEC 61000-4-2 (ESD) ±15kV (Air), ±8kV (Contact)
- Protects Five I/O Lines
- Ultra-Small SC70-6/SC88/SOT363 Package
- Working Voltages: 5V
- Low Leakage Current
- Low Operating and Clamping Voltage
- Solid-State Silicon Avalanche Technology

#### **Pin Configurations**

## **Top View**



#### **Ordering Information**

Part Number	Working Voltage	Packaging Type	Channel	Marking Code	Shipping Qty
UESD6V85CT36	5.0V	SC70-6/SC88/SOT363	5	52C	3000pcs/7Inch Tape & Reel

## **Absolute Maximum Ratings**

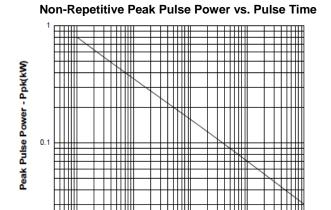
Rating	Symbol	Value	Unit
Peak Pulse Power (t <sub>P</sub> =8/20μs) @ T <sub>A</sub> ≤25°C	$P_{PK}$	140	Watts
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	325	°C/W
Lead Soldering Temperature	$T_{ m L}$	260 (10 sec.)	°C
Operating Temperature	$T_{J}$	-55 to +125	°C
Storage Temperature	$T_{STG}$	-55 to +125	°C
Maximum Junction Temperature	$T_{JMAX}$	150	°C

## **Electrical Characteristics**

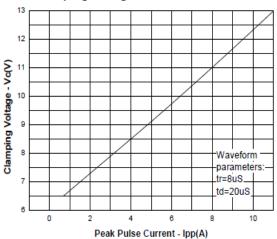
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse Stand-Off Voltage	$V_{RWM}$				5	V
Reverse Breakdown Voltage	$V_{BR}$	I <sub>T</sub> =1mA	6	6.8	7.2	V
Reverse Leakage Current	$I_R$	$V_{RWM}=5V$ , $T=25$ °C			0.1	μΑ
Clamain a Waltaga	$V_{\rm C}$	$I_{PP}=5A, t_{P}=8/20\mu s$			9.1	V
Clamping Voltage		$I_{PP}=11A, t_{P}=8/20 \mu s$			13	V
Iventian Consistence	$C_{\mathrm{J}}$	Pin 1, 3, 4, 5, 6 to 2 V <sub>R</sub> =0V, f=1MHz		40	50	aЕ
Junction Capacitance		Pin 1, 3, 4, 5, 6 to 2 $V_R$ =2.5V, f=1MHz		30	40	pF

0.04 0.1

## **Typical Operating Characteristics**



## Clamping Voltage vs. Peak Pulse Current

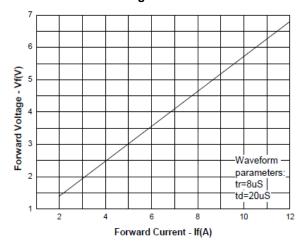


#### Forward Voltage vs. Forward Current

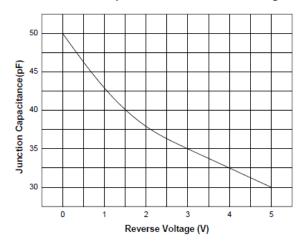
Pulse Duration - tp(uS)

100

1000



#### Junction Capacitance vs. Reverse Voltage





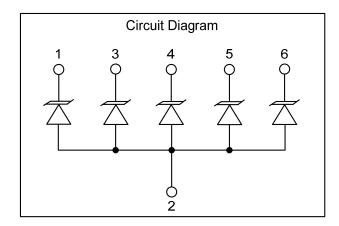
#### **Application Information**

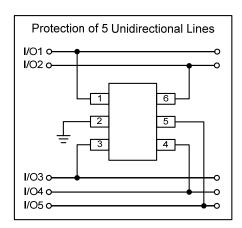
UESD6V85CT36 ESD protection diode is designed to protect 5 data, I/O, or power supply lines. The device is unidirectional and may be used on lines where the signal polarity is above ground. The cathode should be placed towards the line that is to be protected.

#### **Device Connection for Protection of Quad Data Lines**

The UESD6V85CT36 TVS diode array is designed to protect up to five unidirectional data lines. The device as follows:

Unidirectional protection of five I/O lines is achieved by connecting pins 1, 3, 4, 5, and 6 to the data lines. Pin 2 is connected to ground. The ground connection should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.





#### Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

Place the TVS near the input terminals or connectors to restrict transient coupling.

Minimize the path length between the TVS and the protected line.

Minimize all conductive loops including power and ground loops.

The ESD transient return path to ground should be kept as short as possible.

Never run critical signals near board edges.

Use ground planes whenever possible. For multilayer printed-circuit boards, use ground vias.

Keep parallel signal paths to a minimum.

Avoid running protection conductors in parallel with unprotected conductor.

Minimize all printed-circuit board conductive loops including power and ground loops.

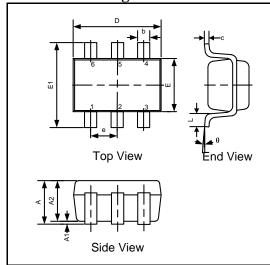
Avoid using shared transient return paths to a common ground point.



# **Package Information**

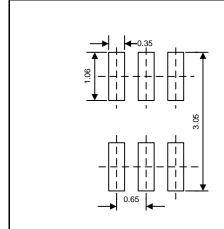
## UESD6V85CT36 SC70-6/SC88/SOT363

#### **Outline Drawing**



DIMENSIONS							
Symbol	MILLIMETERS			INCHES			
	Min	Тур	Max	Min	Тур	Max	
A	0.90	•	1.10	0.035	-	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2	0.90	-	1.00	0.035	-	0.039	
b	0.10	0.25	0.35	0.004	0.010	0.014	
С	0.08	0.11	0.22	0.003	0.004	0.009	
D	1.80	2.15	2.20	0.071	0.085	0.087	
Е	1.15	1.30	1.35	0.045	0.051	0.053	
E1	2.00	-	2.45	0.079	-	0.096	
e	0.65BSC			0.026BSC			
L	0.25	-	0.46	0.010	-	0.018	
θ	0°	-	8°	0°	-	8°	

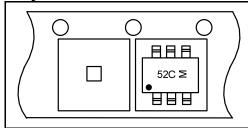
## **Land Pattern**



#### NOTES:

- 1. Compound dimension: 2.15×1.30;
- 2. Unit: mm;
- 3. General tolerance  $\pm 0.05$ mm unless otherwise specified;
- 4. The layout is just for reference.

## **Tape and Reel Orientation**



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